LMV321 SINGLE, LMV358 DUAL, LMV324 QUAD LOW-VOLTAGE RAIL-TO-RAIL OUTPUT OPERATIONAL AMPLIFIERS

SLOS263C - AUGUST 1999 - REVISED MARCH 2000

- 2.7-V and 5-V Performance
- No Crossover Distortion
- Low Supply Current:

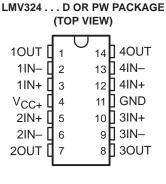
LMV321 . . . 130 μ A Typ LMV358 . . . 210 μ A Typ LMV324 . . . 410 μ A Typ

- Rail-to-Rail Output Swing
- Package Options Include Plastic Small-Outline (D), Small-Outline Transistor (SOT-23 DBV, SC-70 DCK), and Thin Shrink Small-Outline (PW) Packages

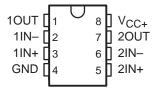
description

The LMV324 and LMV358 are low-voltage (2.7 V to 5.5 V) versions of the dual and quad operational amplifiers, LM324 and LM358, that operate from 5 V to 30 V. The LMV321 is the single-amplifier version.

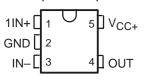
The LMV321, LMV324, and LMV358 are the most cost-effective solutions for applications where low-voltage operation, space saving, and low price are needed. They offer specifications that meet or exceed those of the familiar LM358 and LM324 devices. These devices have rail-to-rail output-swing capability, and the input common-mode voltage range includes ground. They all exhibit excellent speed-to-power ratios, achieving 1MHz of bandwidth at 1-V/μs slew rate with low supply current.







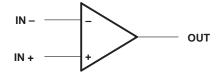
LMV321 . . . DBV OR DCK PACKAGE (TOP VIEW)



The LMV321 is available in the ultra-small DCK package, which is approximately one-half the size of the DBV package. This package saves space on printed circuit boards and enables the design of small portable electronic devices. It also allows the designer to place the device closer to the signal source to reduce noise pickup and increase signal integrity.

The LMV321I, LMV324I, and LMV358I devices are characterized for operation from -40°C to 85°C.

symbol (each amplifier)



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AVAILABLE OPTIONS

т.	PACKAGE	PACKAGED DEVICES				
TA	TYPE	SINGLE	DUAL	QUADRUPLE		
	5-pin SOT	LMV321IDCKR LMV321IDBVR		_ _		
-40°C to 85°C	8-pin SOIC 8-pin TSSOP	_ _	LMV358ID LMV358IPWR	_ _		
	14-pin SOIC 14-pin TSSOP	_ _	_	LMV324ID LMV324IPWR		

The D package is available taped and reeled. Add the suffix R to the device type (e.g., LMV324DR). The DCK, DBV, and PW packages are only available left-end taped and reeled.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V _{CC} (see Note 1)	0 to	±5.5 V
V _{CC} ≤ 5.5 V (see Note 3)	, , , ,	limited
Operating virtual junction temperature		
Package thermal impedance, θ_{JA} (see Notes 4 and 5):	D (8-pin) package 19	7°C/W
	D (14-pin) package 12	7°C/W
	DBV package 34	7°C/W
	DCK package 38	9°C/W
	PW (8-pin) package 24	3°C/W
	PW (14-pin) package 17	0°C/W
Lead temperature 1,6 mm (1/16 inch) from case for 10 s	seconds: D or PW package	260°C
	DBV or DCK package	. TBD
Storage temperature range, T _{stg}	–65 to	150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values (except differential voltages and V_{CC} specified for the measurement of I_{OS}) are with respect to the network GND.

- 2. Differential voltages are at IN+ with respect to IN-.
- 3. Short circuits from outputs to V_{CC} can cause excessive heating and eventual destruction.
- 4. Maximum power dissipation is a function of $T_J(max)$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) - T_A)/\theta_{JA}$. Selecting the maximum of 150°C can impact reliability.
- 5. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions

		MIN	MAX	UNIT
Vcc	Supply voltage (single-supply operation)	2.7	5.5	V
TA	Operating free-air temperature	-40	85	°C



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electrical characteristics at T_A = 25°C and V_{CC+} = 2.7 V (unless otherwise noted)

PARAMETER		TEST COND	MIN	TYP	MAX	UNIT	
VIO	Input offset voltage				1.7	7	mV
$\alpha_{V_{IO}}$	Average temperature coefficient of input offset voltage				5		μV/°C
I _{IB}	Input bias current				11	250	nA
lιο	Input offset current				5	50	nA
CMRR	Common-mode rejection ratio	$V_{CM} = 0 \text{ to } 1.7 \text{ V}$	V _{CM} = 0 to 1.7 V		63		dB
ksvr	Supply-voltage rejection ratio	$V_{CC} = 2.7 \text{ V to 5 V},$	V _O = 1 V	50	60		dB
VICR	Common-mode input voltage range	CMRR ≥ 50 dB		0 to 1.7	-0.2 to 1.9		V
	Output swing	D 40104-405V	High level	V _{CC} -100	V _{CC} -10		mV
		$R_L = 10 \text{ k}\Omega \text{ to } 1.35 \text{ V}$	Low level		60	180	IIIV
	Supply current	LMV321I		80	170		
Icc		LMV358I (both amplifier		140	340	-l ' l	
		LMV324I (all four amplifi		260	680		
B ₁	Unity-gain bandwidth	C _L = 200 pF		1		MHz	
Φ_{m}	Phase margin				60		deg
Gm	Gain margin				10		dB
٧n	Equivalent input noise voltage	f = 1 kHz			46		nV/√ Hz
In Equivalent input noise current		f = 1 kHz		0.17		pA/√Hz	

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electrical characteristics at specified free-air temperature range, $V_{CC+} = 5 \text{ V}$ (unless otherwise noted)

PARAMETER		TEST CONDITIONS		TA	MIN	TYP	MAX	UNIT
Via Input offset voltege				25°C		1.7	7	mV
VIO	Input offset voltage			–40°C to 85°C			9	IIIV
$\alpha_{V_{IO}}$	Average temperature coefficient of input offset voltage			25°C		5		μV/°C
1.5	Input bigg gurrant			25°C		15	250	nA
IB	Input bias current		Ţ.				500	IIA
li o	Input offset current			25°C		5	50	nA
lio	input onset current			–40°C to 85°C			150	IIA
CMRR	Common-mode rejection ratio	V _{CM} = 0 to 4 V		25°C	50	65		dB
ksvr	Supply-voltage rejection ratio	V _{CC} = 2.7 V to 5 V, V _O = 1 V, V _{CM} = 1 V		25°C	50	60		dB
VICR	Common-mode input voltage range	CMMR ≥ 50 dB		25°C	0 to 4	-0.2 to 4.2		V
			Lligh lovel	25°C	V _{CC} -300	V _{CC} -40		
		$R_L = 2 k\Omega$ to 2.5 V	High level	-40°C to 85°C	V _{CC} -400			
	Output swing		Low level	25°C		120	300	
				-40°C to 85°C			400	mV
		R _L = 10 kΩ to 2.5 V	High level	25°C	V _{CC} -100	V _{CC} -10		IIIV
				–40°C to 85°C	V _{CC} -200			
				25°C		65	180	
				–40°C to 85°C			280	
Δ, τρ	Large-signal differential	R _L = 2 kΩ		25°C	15	100		V/mV
AVD	voltage gain	KL = 2 K22		–40°C to 85°C	10			V/mV
loo	Output short-circuit current	Sourcing, V _O = 0 V		25°C	5	60		mA
los	Output short-circuit current	Sinking, $V_0 = 5 V$		25 0	10	160		mA
	Supply current	LMV321I		25°C		130	250	
				–40°C to 85°C			350	μΑ
loc		LMV358I (both amplifiers)		25°C		210	440	
Icc				–40°C to 85°C			615	
		LMV324I (all four amplifiers)		25°C		410	830	
				–40°C to 85°C			1160	
B ₁	Unity-gain bandwidth	C _L = 200 pF		25°C		1		MHz
φm	Phase margin			25°C		60		deg
G _m	Gain margin			25°C		10		dB
٧n	Equivalent input noise voltage	f = 1 kHz		25°C		39		nV/√Hz
In	Equivalent input noise current	f = 1 kHz		25°C		0.21		pA/√Hz
SR	Slew rate			25°C		1		V/μs



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